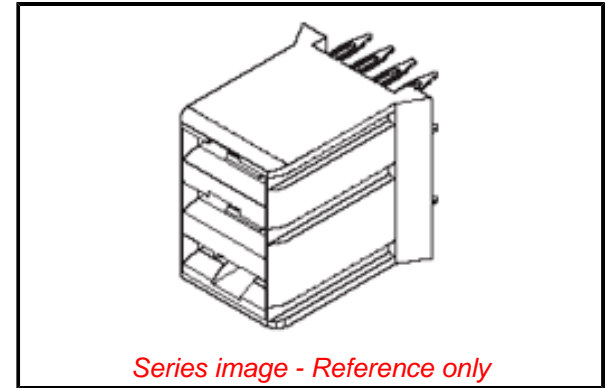


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Part Number: **0736560000**
Status: **Active**
Overview: HDM Backplane Connector System
Description: HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm

Documents:

3D Model	Packaging Specification PK-70873-0819 (PDF)
Drawing (PDF)	Test Summary TS-73656-001 (PDF)
Product Specification PS-73670-9999 (PDF)	RoHS Certificate of Compliance (PDF)
Application Specification AS-73656-1998-001 (PDF)	



Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	<u>73656</u>
Application	Backplane
Comments	Backplane Power Module
Component Type	Power Header
Overview	<u>HDM Backplane Connector System</u>
Product Name	HDM
UPC	800754345361

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	1.609/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	3.70mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
ED/61/2018 (27 June
2018)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

China RoHS

Green Image

Not Relevant

Not Contained

Search Parts in this Series

73656 Series

Mates With

73651 HDM Board-to-Board Daughterboard Power Module

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description

Product #

HDM Power Module	<u>621001100</u>
Removal Tool	
Backplane Power	<u>622005711</u>
Module Loading	
Heads	

Termination Interface: Style Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact 15.0A
Data Rate 1.0 Gbps
Voltage - Maximum 500V AC

Solder Process Data

Lead-freeProcess Capability N/A

Material Info

Reference - Drawing Numbers

Application Specification AS-73656-1998-001
Packaging Specification PK-70873-0819
Product Specification PS-73670-9999
Sales Drawing SDA-73656-*00*
Test Summary TS-73656-001

This document was generated on 11/26/2018

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